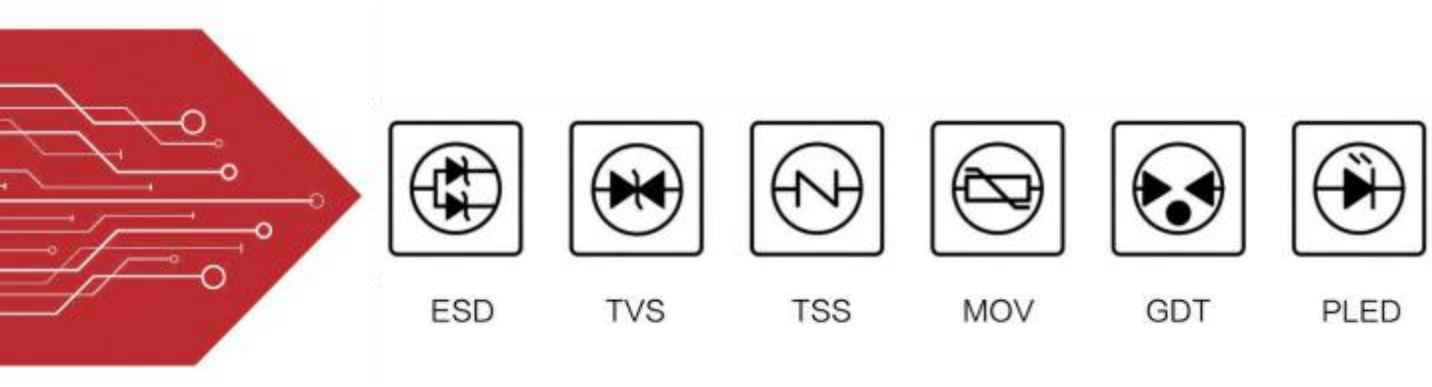
MSKSEMI
SEMICONDUCTOR



Product data sheet

SOT-23-3L SOT-89

1. GND 2. OUT 3. IN

FEATURES

Maximum output current

I_{OM}: 0.1A

Output voltage

V_o:-5V

Continuous total dissipation

P_D : SOT-23-3L 0.35 W (T_a = 25 ℃)

SOT-89 0.5 W (T_a= 25 ℃)

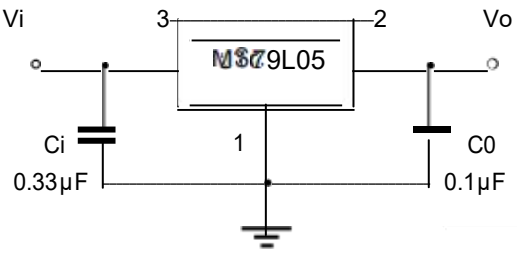
ABSOLUTE MAXIMUM RATINGS (Operating temperature range applies unless otherwise specified)

Parameter	Symbol	Value	Units
Input Voltage	V_i	-30	V
Operating Junction Temperature Range	T_{OPR}	0~+125	℃
Storage Temperature Range	T_{STG}	-55~+150	℃

ELECTRICAL CHARACTERISTICS AT SPECIFIED VIRTUAL JINCTION TEMPERATURE(VI=-10V,Io=40mA,Ci=0.33μF,Co=0.1μF, unless otherwise specified)

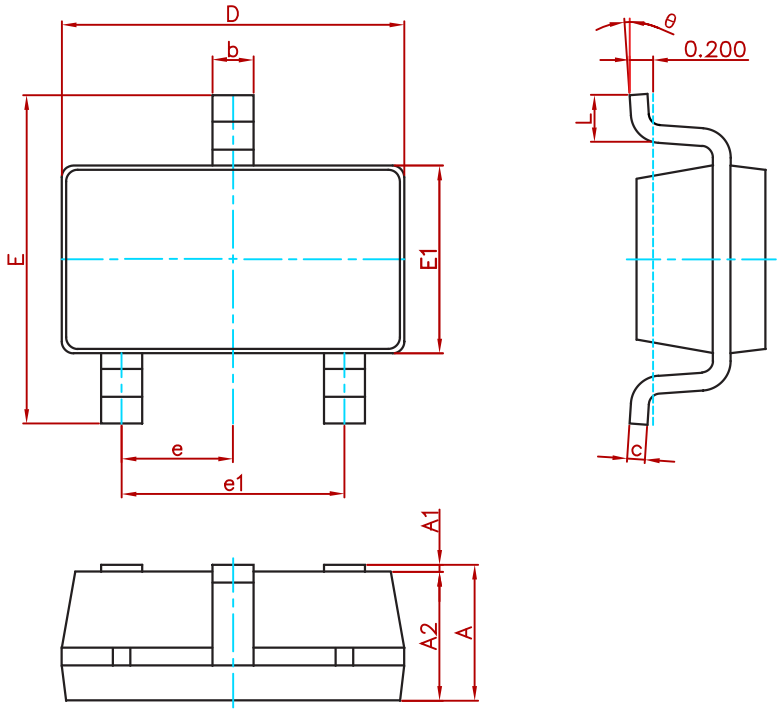
Parameter	Symbol	Test conditions		MIN	TYP	MAX	UNIT
Output voltage	Vo		25℃	-4.8	-5.0	-5.2	V
		-7V≤V I≤-20V, Io=1mA~40mA	0-125℃	-4.75	-5.0	-5.25	V
		Io=1mA~70mA		-4.75	-5.0	-5.25	V
Load Regulation	ΔVo	Io=1mA~100mA	25℃		20	60	mV
		Io=1mA~40mA	25℃		10	30	mV
Line regulation	ΔVo	-7V≤V I≤-20V	25℃		15	150	mV
		-8V≤V I≤-20V	25℃		12	100	mV
Quiescent Current	Iq		25℃			6	mA
Quiescent Current Change	ΔIq	-8V≤V I≤-20V	0-125℃			1.5	mA
	ΔIq	1mA≤V I≤40mA	0-125℃			0.1	mA
Output Noise Voltage	V_N	10Hz≤f≤100KHz	25℃		40		uV
Ripple Rejection	RR	-8V≤V I≤-18V,f=120Hz	0-125℃	41	49		dB
Dropout Voltage	Vd		25℃		1.7		V

TYPICAL APPLICATION



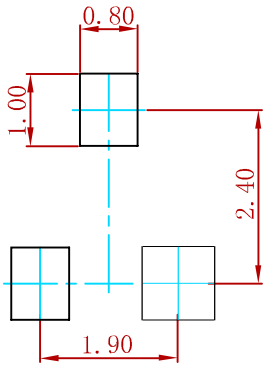
Note : Bypass capacitors are recommended for optimum stability and transient response and should be located as close as Possible to the regulators.

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout

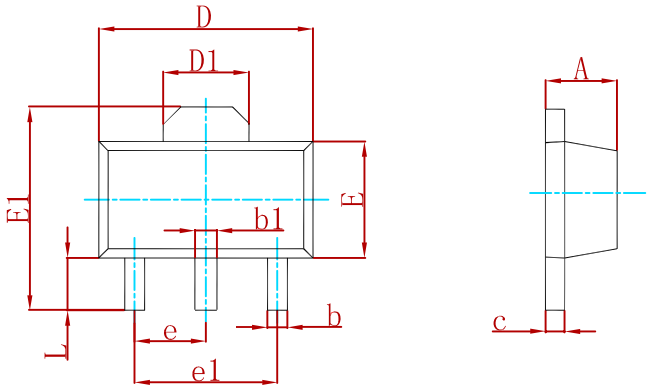


Note:
1.Controlling dimension:In millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

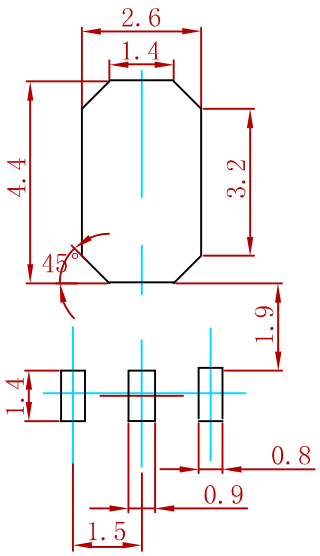
P/N	PKG	QTY
MS79L05S	SOT-23-3L	3000

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047

Suggested Pad Layout



Note:
1.Controlling dimension:In millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MS79L05	SOT-89	1000

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